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MUETING & RAASCH

**Amendment and Response Under 37 C.F.R. §1.116 - Expedited Examining Procedure**

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Serial N : 09/759,993

Confirmation No.: 1053

Filed: 12 January 2001

For: **ADHESIVE FILM REMOVAL METHOD AND APPARATUS**

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26. (NEW) A method of removing adhesive film from a substrate, the adhesive film comprising first and second ends defining a length and a width transverse to the length, the method comprising:

    applying tension over the width of the adhesive film to remove the adhesive film from the substrate along a release line;

    transferring the tension onto the substrate in the form of a compressive force, wherein the compressive force is applied to the substrate at a distance from the release line;

    varying the distance between the compressive force and the release line; and

    advancing the release line and the compressive force towards the second end of the adhesive film, whereby the adhesive film is removed from the substrate.

27. (NEW) A method according to claim 26, wherein the compressive force is applied to the substrate behind the release line as the release line advances toward the second end of the adhesive film.

28. (NEW) A method according to claim 26, wherein the compressive force is applied to the substrate ahead of the release line as the release line advances toward the second end of the adhesive film.

29. (NEW) A method according to claim 26, wherein applying tension over the width of the adhesive film comprises attaching the adhesive film to a winding roll and winding the adhesive film thereon, and further wherein the compressive force is applied to the substrate by a support roll, and further wherein the winding roll and the support roll are located a fixed distance apart.

30. (NEW) A method according to claim 26, further comprising heating the adhesive film before removing the adhesive film from the substrate along the release line.

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31. (NEW) A method of removing adhesive film from a substrate, the adhesive film comprising first and second ends defining a length and a width transverse to the length, the method comprising:

applying tension over the width of the adhesive film to remove the adhesive film from the substrate along a release line;

transferring the tension onto the substrate in the form of a compressive force, wherein the compressive force is applied to the substrate at a distance from the release line;

varying the distance between the compressive force and the release line by varying the tension applied to the adhesive film; and

advancing the release line and the compressive force towards the second end of the adhesive film, whereby the adhesive film is removed from the substrate.

32. (NEW) A method according to claim 31, wherein the compressive force is applied to the substrate behind the release line as the release line advances toward the second end of the adhesive film.

33. (NEW) A method according to claim 31, wherein the compressive force is applied to the substrate ahead of the release line as the release line advances toward the second end of the adhesive film.

34. (NEW) A method according to claim 31, wherein applying tension over the width of the adhesive film comprises attaching the adhesive film to a winding roll and winding the adhesive film thereon, and further wherein the compressive force is applied to the substrate by a support roll, and further wherein the winding roll and the support roll are located a fixed distance apart.

35. (NEW) A method according to claim 31, further comprising heating the adhesive film before removing the adhesive film from the substrate along the release line.

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36. (NEW) A method of removing adhesive film from a substrate, the adhesive film comprising first and second ends defining a length and a width transverse to the length, the method comprising:

attaching the first end of the adhesive film to a winding device;

rotating the winding device to apply tension over the width of the adhesive film to remove the adhesive film from the substrate along a release line;

transferring the tension applied to the adhesive film onto the substrate in the form of a compressive force, with the compressive force being applied to the substrate by the winding device and wherein the compressive force is applied to the substrate at a distance from the release line;

varying the distance between the compressive force and the release line; and

advancing the release line towards the second end of the adhesive film while winding the adhesive film on the winding device, whereby the adhesive film is removed from the substrate.

37. (NEW) A method according to claim 36, wherein the compressive force is applied to the substrate behind the release line as the release line advances toward the second end of the adhesive film.

38. (NEW) A method according to claim 36, wherein the compressive force is applied to the substrate ahead of the release line as the release line advances toward the second end of the adhesive film.

39. (NEW) A method according to claim 36, further comprising heating the adhesive film before removing the adhesive film from the substrate along the release line.

40. (NEW) A method of removing adhesive film from a substrate, the adhesive film comprising first and second ends defining a length and a width transverse to the length, the method comprising:

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- attaching the first end of the adhesive film to a winding device;
- rotating the winding device to apply tension over the width of the adhesive film to remove the adhesive film from the substrate along a release line;
- transferring the tension applied to the adhesive film onto the substrate in the form of a compressive force, with the compressive force being applied to the substrate by the winding device and wherein the compressive force is applied to the substrate at a distance from the release line;
- varying the distance between the compressive force and the release line by varying the speed at which the winding device is rotated; and
- advancing the release line towards the second end of the adhesive film while winding the adhesive film on the winding device, whereby the adhesive film is removed from the substrate.
41. (NEW) A method according to claim 40, wherein the compressive force is applied to the substrate behind the release line as the release line advances toward the second end of the adhesive film.
42. (NEW) A method according to claim 40, wherein the compressive force is applied to the substrate ahead of the release line as the release line advances toward the second end of the adhesive film.
43. (NEW) A method according to claim 40, further comprising heating the adhesive film before removing the adhesive film from the substrate along the release line.